

CLAIMS

1. An electronic device sealing resin sheet,
comprising a first resin layer and a second resin layer,
5 wherein the first resin layer has a thermal
conductivity of 1 W/mK or more; and
wherein in a region of the first resin layer which is
to be diced, a resin layer is formed, the resin layer being
a layer in which the content of the thermally conductive
10 particles is 30% by volume or less.

2. The electronic device sealing resin sheet
according to claim 1,
wherein the first resin layer comprises thermally
15 conductive particles, and
the content of the thermally conductive particles in
the first resin layer is from 55 to 83% by volume.

3. The electronic device sealing resin sheet
20 according to claim 1 or 2, wherein the thermally conductive
particles are alumina and/or boron nitride.

~~4. The electronic device sealing resin sheet
according to any one of claims 1 to 3, wherein in a region
25 of the first resin layer which is to be diced, a resin
layer is formed, the resin layer being a layer in which the
content of the thermally conductive particles is 30% by
volume or less.~~

30 45. A method for manufacturing an electronic device
package, comprising the step of sealing an electronic

device with the electronic device sealing resin sheet
| recited in any one of claims 1 to 34 to bring the first
resin layer into contact with the electronic device.